EU-Singapore Joint Researchers Workshop on Semiconductor

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State of play of the European Chips Act

European Semiconductor Board (Governance)

Pillar 1

Chips for Europe Initiative

- Initiative on infrastructure building in synergy with the EU's research programmes
- Support to start-ups and SMEs

Pillar 2

Security of Supply

- First-of-a-kind semiconductor production facilities

Pillar 3

Monitoring and Crisis Response

- Monitoring and alerting
- Crisis coordination mechanism with MS
- Strong Commission powers in times of crisis

Research policy + Industry policy + Crisis management strategy

European Commission

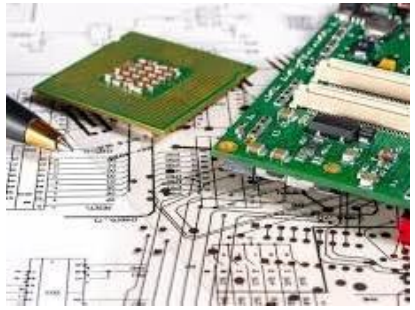
Pillar I – Chips for Europe Initiative

Infrastructures open to a wide range of EU users

5 launched

Pilot lines

Prototyping of validated designs
Testing of equipment
Validation of process flows



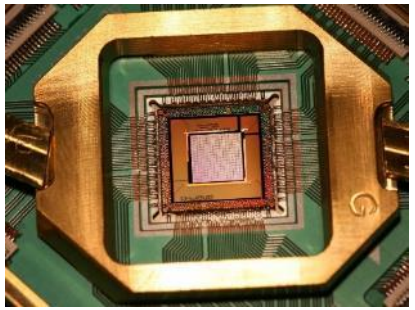
Design Platform

Help designing semiconductor devices, via access to Electronic Design Automation tools and IP libraries

Operational summer 2026

Competence centres

Access to technical expertise, helping companies to approach and improve design capabilities and developing skills

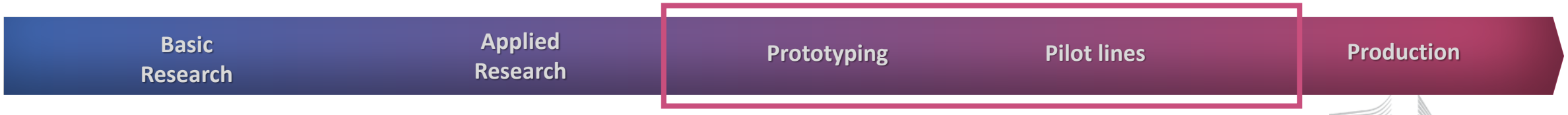


Quantum chips

Technology and engineering capacities for accelerating innovative development of quantum chips

6 quantum chips pilots selected

27+ launched



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Pillar II – Security of supply and resilience

State aid for production facilities

First-of-a-kind facility (FOAK): offers innovation in terms of products or process (e.g. environmental performance) not yet present in the Union

All stages of semiconductor production are eligible

Wafer production → **Wafer processing** → **IC packaging / assembly**

Planned investments by major manufacturers exceeding **EUR 80 Billion**

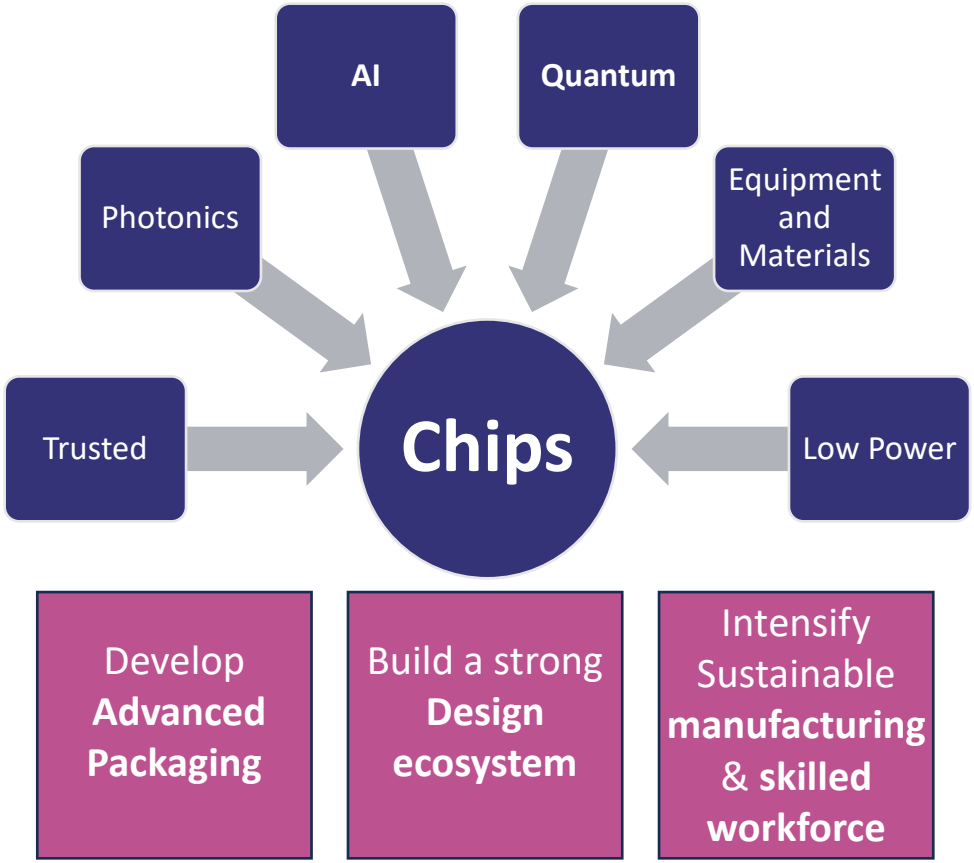
The Commission ***approved*** state aid for the following projects so far:

Company	MS	Location	Investment (EUR Billion)	Technology
ST Microelectronics	IT	Catania	0.73	SiC wafer
ST Micro & GlobalFoundries	FR	Crolles	7.5	300-mm FD-SOI
ST Microelectronics	IT	Catania	5	SiC devices
ESMC (J.V. TSMC + Bosch/Infineon/NXP)	DE	Dresden	>10	CMOS, FinFET
Silicon Box	IT	Novara	3.2	Advanced packaging
Infineon	DE	Dresden	4.46	Discrete, analog/mixed signals
ams Osram	AT	Premstätten	0.567	CMOS
			EUR 31.5 Bn	

More projects in the pipeline,
Further, IPCEI ME-CT started in 2023 with over **EUR 21 Billion** investments

European Commission

Possible Future Priorities



Verticals

- Automotive
- Industrial automation
- Data infrastructure / Edge AI
- Telecom
- Aerospace Security & Defence
- Healthcare
- Energy

- Need to address strategic priorities, critical dependencies, and industry verticals
- Strengthen our competencies on **essential chips** and develop novel capacities on **cutting-edge chips**
- Attracting **investments**

European Commission

EU-Singapore cooperation

DG CNECT contributed to the **SEMICON Southeast Asia 2025,** the region's premier semiconductor industry event taking place this year in Singapore, with a vision of "Stronger Together" and an attendance of over 20,000 participants from the SEA region and worldwide

On R&I

Leveraging the EU-Singapore Digital Partnership, both parties can deepen collaboration in research and development, focusing on chip technologies on mature node size platforms such as photonics, sensing and packaging including for emerging applications in AI and quantum computing.

On investments

Both ecosystems benefit from mutual investments, enhancing overall supply chain resilience.

Examples: Soitec, Silicon Box, NXP, ST, Infineon